

Electronic Patent Application Fee Transmittal

Application Number:	10722288				
Filing Date:	25-Nov-2003				
Title of Invention:	THERMAL INTERFACE MATERIAL AND SOLDER PREFORMS				
First Named Inventor/Applicant Name:	Brian G. Lewis				
Filer:	Andrew C. Wegman/Valarie McLaurin				
Attorney Docket Number:	CEDA 7000.5				
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Utility Filing Fees					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:					
Pages:					
Claims:					
Claims in excess of 20		1202	31	50	1550
Miscellaneous-Filing:					
Petition:					
Patent-Appeals-and-Interference:					
Post-Allowance-and-Post-Issuance:					
Extension-of-Time:					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1550